

https://www.phoenixcontact.com/us/products/1822927



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PCB terminal block, nominal current: 17.5 A, rated voltage (III/2): 160 V, nominal cross section: 1.5 mm², number of potentials: 8, number of rows: 1, number of positions per row: 8, product range: SPT 1,5/..-H-THR, pitch: 3.81 mm, connection method: Push-in spring connection, mounting: THR soldering, conductor/PCB connection direction: 0 °, color: black, Pin layout: Linear pinning, Solder pin [P]: 2.6 mm, number of solder pins per potential: 2, type of packaging: packed in cardboard

Your advantages

- · Time saving push-in connection, tools not required
- · Defined contact force ensures that contact remains stable over the long term
- · Intuitive operation due to color-coded actuating push button
- · Designed for integration into the SMT soldering process
- Quick and convenient testing using integrated test option
- · Operation and conductor connection from one direction enable integration into front of device
- · Two solder pins reduce the mechanical strain on the soldering spots

Commercial data

Item number	1822927
Packing unit	80 pc
Minimum order quantity	80 pc
Note	Made to order (non-returnable)
Sales key	AA12
Product key	AALCCD
Catalog page	Page 10 (NTK-2014)
GTIN	4046356811453
Weight per piece (including packing)	5 g
Weight per piece (excluding packing)	5 g
Customs tariff number	85369010
Country of origin	PL



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Technical data

Product properties

Product type	Printed circuit board terminal
Product family	SPT 1,5/H-THR
Product line	COMBICON Terminals S
Number of positions	8
Pitch	3.81 mm
Number of connections	8
Number of rows	1
Number of potentials	8
Pin layout	Linear pinning
Solder pins per potential	2

Electrical properties

Nominal current I _N	17.5 A
Nominal voltage U _N	160 V
Degree of pollution	3
Rated voltage (III/3)	160 V
Rated surge voltage (III/3)	2.5 kV
Rated voltage (III/2)	160 V
Rated surge voltage (III/2)	2.5 kV
Rated voltage (II/2)	320 V
Rated surge voltage (II/2)	2.5 kV

Connection data

Connection technology	
Nominal cross section	1.5 mm²
Conductor connection	
Connection method	Push-in spring connection
Conductor cross section rigid	0.2 mm² 1.5 mm²
Conductor cross section flexible	0.2 mm ² 1.5 mm ²
Conductor cross section AWG	24 16
Conductor cross section flexible, with ferrule without plastic sleeve	0.2 mm ² 1.5 mm ²
Conductor cross section, flexible, with ferrule, with plastic sleeve	0.2 mm ² 0.75 mm ²
Stripping length	8 mm

Mounting

Mounting type	THR soldering
Pin layout	Linear pinning

Processing notes





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Process	Reflow/wave soldering
Moisture Sensitive Level	MSL 1
Classification temperature T _c	260 °C
Solder cycles in the reflow	3

Material specifications

Material data - contact	
Note	WEEE/RoHS-compliant, free of whiskers according to IEC 60068-2-82/JEDEC JESD 201
Contact material	Cu alloy
Surface characteristics	hot-dip tin-plated
Metal surface terminal point (top layer)	Tin (4 - 8 μm Sn)
Metal surface soldering area (top layer)	Tin (4 - 8 μm Sn)
Material data - housing	
Color (Housing)	black (9005)
Insulating material	LCP
Insulating material group	llia
CTI according to IEC 60112	175
Flammability rating according to UL 94	VO
Material data – actuating element	
Color (Actuating element)	white (9010)
Insulating material	PAGF
Insulating material group	1
CTI according to IEC 60112	600
Flammability rating according to UL 94	VO

Notes

Assembly instruction:	This item is not suitable for PCB cleaning with liguids.

Dimensions

Dimensional drawing	
Pitch	3.81 mm
Width [w]	30.67 mm
Height [h]	10.3 mm
Length [I]	13.6 mm
Installed height	7.7 mm
Solder pin length [P]	2.6 mm
Pin dimensions	0.7 x 0.3 mm



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CB design	
Pin spacing	7 mm
Hole diameter	1.1 mm
chanical tests	
onnection test	
Specification	IEC 60998-2-2:2002-12
Result	Test passed
est for conductor damage and slackening	
Specification	IEC 60998-2-2:2002-12
Result	Test passed
ul out toot	
ull-out test	IEC 60998-2-2:2002-12
Specification	0.2 mm ² / solid / > 10 N
Conductor cross section/conductor type/tractive force setpoint/actual value	0.2 mm ² / solid / > 10 N
	1.5 mm ² / solid / > 40 N
	1.5 mm^2 / flexible / > 40 N
exion test	
Specification	IEC 60998-2-2:2002-12
Result	Test passed
sulation holder for crimp connections	
Result	Test passed
ctrical tests	
emperature-rise test	
emperature-rise test Specification	IEC 60947-7-4:2019-01
	IEC 60947-7-4:2019-01 The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature.
Specification Requirement temperature-rise test	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting
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Specification Requirement temperature-rise test sulation resistance Specification Insulation resistance, neighboring positions r clearances and creepage distances	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60998-1:2002-12 > 5 MΩ
Specification Requirement temperature-rise test sulation resistance Specification Insulation resistance, neighboring positions r clearances and creepage distances Specification	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60998-1:2002-12 > 5 MΩ IEC 60947-7-4:2013-08
Specification Requirement temperature-rise test sulation resistance Specification Insulation resistance, neighboring positions r clearances and creepage distances Specification Insulating material group	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60998-1:2002-12 > 5 MΩ IEC 60947-7-4:2013-08 IIIa
Specification Requirement temperature-rise test sulation resistance Specification Insulation resistance, neighboring positions r clearances and creepage distances Specification Insulating material group Comparative tracking index (IEC 60112)	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60998-1:2002-12 > 5 MΩ IEC 60947-7-4:2013-08 IIIa CTI 175
Requirement temperature-rise test sulation resistance Specification Insulation resistance, neighboring positions ir clearances and creepage distances Specification Insulating material group Comparative tracking index (IEC 60112) Rated insulation voltage (III/3)	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60998-1:2002-12 > 5 MΩ IEC 60947-7-4:2013-08 IIIa CTI 175 160 V



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Rated insulation voltage (III/2)	160 V
Rated surge voltage (III/2)	2.5 kV
minimum clearance value - non-homogenous field (III/2)	1.5 mm
minimum creepage distance (III/2)	1.6 mm
Rated insulation voltage (II/2)	320 V
Rated surge voltage (II/2)	2.5 kV
minimum clearance value - non-homogenous field (II/2)	1.5 mm
minimum creepage distance (II/2)	3.2 mm

Environmental and real-life conditions

Specification	IEC 60068-2-6:2007-12
Frequency	10 - 150 - 10 Hz
Sweep speed	1 octave/min
Amplitude	0.35 mm (10 Hz 60.1 Hz)
Sweep speed	5g (60.1 Hz 150 Hz)
Test duration per axis	2.5 h
ow-wire test	
Specification	IEC 60998-1:2002-12
Temperature	850 °C
Time of exposure	5 s
bient conditions	
Ambient temperature (operation)	-40 °C 105 °C (Depending on the current carrying capacity/derating curve)
Ambient temperature (storage/transport)	-40 °C 70 °C
Relative humidity (storage/transport)	30 % 70 %

Type of packaging	packed in cardboard
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